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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET VO	ga	
09/854,539	05/14/2001	Steven Towle	ATTORNEY DOCKET NO.	CONFIRMATION NO.	
	05/14/2001		884.415US1	8328	
	7590 04/26/2004			EXAMINER	
Schwegman, Lunberg, Woessner & Kluth, P.A. P.O. Box 2938			PERALTA, GINETTE		
Minneapolis, MN 55402			ART UNIT	PAPER NUMBER	
			2814		

DATE MAILED: 04/26/2004

Please find below and/or attached an Office communication concerning this application or proceeding.

Attachn	nent(s)

- 1) Notice of References Cited (PTO-892)
- 2) Notice of Draftsperson's Patent Drawing Review (PTO-948)
- 3) Information Disclosure Statement(s) (PTO-1449 or PTO/SB/08) Paper No(s)/Mail Date 2/04.

4) 🔲	Interview Summary (PTO-413)
	Paper No(s)/Mail Date.

5) Notice of Informal Patent Application (PTO-152)

6) Other: \_\_\_\_

\* See the attached detailed Office action for a list of the certified copies not received.

- 1. The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:
  - (a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negatived by the manner in which the invention was made.
- 2. Claims 1-3, 5 and 9-11 are rejected under 35 U.S.C. 103(a) as being unpatentable over Marrs et al. (U. S. Pat. 5,355,283) in view of Sawada (U. S. Pat. 5,424,250).

Regarding claim 1, Marrs et al. discloses in Fig. 5 a microelectronic device comprising a package core 502 having an opening therein; a microelectronic die 501 located within the opening of the package core 502; and an encapsulation material 503 within the opening of the package core to hold the microelectronic die within the package core 502, the encapsulation material including a polymeric resin more specifically a molding or potting resin such as epoxy (col. 8, Il. 30-35).

Marrs et al. disclosed the claimed invention with the exception of using a fiber reinforced encapsulation material.

Sawada discloses a fiber reinforced encapsulation material used in microelectronic device package to hold a microelectronic die within the package, the fiber reinforced encapsulation material including a polymeric resin having a fibrous filler material wherein the fiber reinforced encapsulation material is taught and used for

Art Unit: 2814

the disclosed intended purpose of providing a molding using resin having a smaller coefficient of thermal expansion so that a package having high mechanical strength and small thermal stress is obtained.

Thus, it would have been obvious to one of ordinary skill in the art at the time the invention was made to use a fiber reinforced polymeric resin as the one taught by Sawada as the molding resin of Marrs et al. for the disclosed intended purpose of Sawada of providing a molding using resin having a smaller coefficient of thermal expansion so that a package having high mechanical strength and small thermal stress is obtained , and furthermore providing an encapsulant capable of good mechanical properties, having high heat distortion temperatures, and providing cured products exhibiting reduced shrinkage and improved surface appearance.

Regarding claims 2 and 3, Sawada does not disclose the fibers length or width. It would have been obvious to one having ordinary skill in the art at the time of the invention was made to depending on the use of the fiber reinforced resin to vary the length of the particles of individual fibers, as there is no statement denoting the criticality of the fiber width and thickness and as Sawada discloses that the fibers are part of a molding used to encapsulate a semiconductor die.

"In the case where the claimed ranges "overlap or lie inside ranges disclosed by the prior art" a prima facie case of obviousness exists. In re Wertheim, 541 F.2d 257, 191 USPQ 90 (CCPA 1976); In re Woodruff, 919 F.2d 1575, 16 USPQ2d 1934 (Fed. Cir. 1990) (The prior art taught carbon monoxide concentrations of "about 1-5%" while the claim was limited to "more than 5%." The court held that "about 1-5%" allowed for concentrations slightly above 5% thus the ranges overlapped.)" (MPEP 2144.04)

Art Unit: 2814

Regarding claim 5, Sawada discloses that the fibrous filler material includes carbon-containing fibers.

Regarding claims 9 and 10, Marrs et al. and Sawada disclose the polymeric resin including epoxy or a plastic.

Regarding claim 11, Marrs et al. discloses the structure further comprising a metallization layer 504 built up over the package core 502, the metallization layer being conductively coupled to bond pads 508 on a surface of the microelectronic die.

## Response to Arguments

3. Applicant's arguments with respect to claims 1-3, 5, and 9-11 have been considered but are moot in view of the new ground(s) of rejection.

## Conclusion

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Ginette Peralta whose telephone number is (571)272-1713. The examiner can normally be reached on Monday to Friday 8:00 AM- 5:30 PM.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Wael Fahmy can be reached on (571)272-1705. The fax phone number for the organization where this application or proceeding is assigned is 703-872-9306.

Application/Control Number: 09/854,539 Page 5

Art Unit: 2814

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see http://pair-direct.uspto.gov. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free).

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